### 查询TLC5628CDW供应商

# 捷多邦,专业PCB打样工厂,24**小社①5628€**, TLC5628I OCTAL 8-BIT DIGITAL-TO-ANALOG CONVERTERS

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- Eight 8-Bit Voltage Output DACs N OR DW PACKAGE (TOP VIEW) 5-V Single-Supply Operation Serial Interface 16 DACC DACB [ **High-Impedance Reference Inputs** 15 DACD DACA 2 Programmable 1 or 2 Times Output Range GND 3 14 REF1 DATA 1 4 13 LDAC Simultaneous Update Facility CLK [ 12 LOAD 5 **Internal Power-On Reset** 11 REF2 V<sub>DD</sub> 6 **Low-Power Consumption** WWW.DZSC.COM DACE 👖 7 10 DACH Half-Buffered Output DACF [ 9 DACG 8 applications
  - Programmable Voltage Sources
  - Digitally Controlled Amplifiers/Attenuators
  - Mobile Communications
  - Automatic Test Equipment
  - Process Monitoring and Control
  - Signal Synthesis

#### description

The TLC5628C and TLC5628I are octal 8-bit voltage output digital-to-analog converters (DACs) with buffered reference inputs (high impedance). The DACs produce an output voltage that ranges between either one or two times the reference voltages and GND and are monotonic. The device is simple to use, running from a single supply of 5 V. A power-on reset function is incorporated to ensure repeatable start-up conditions.

Digital control of the TLC5628C and TLC5628I are over a simple three-wire serial bus that is CMOS compatible and easily interfaced to all popular microprocessor and microcontroller devices. The 12-bit command word comprises eight bits of data, three DAC select bits, and a range bit, the latter allowing selection between the times 1 or times 2 output range. The DAC registers are double buffered, allowing a complete set of new values to be written to the device, then all DAC outputs are updated simultaneously through control of LDAC. The digital inputs feature Schmitt triggers for high-noise immunity.

The 16-terminal small-outline (D) package allows digital control of analog functions in space-critical applications. The TLC5628C is characterized for operation from 0°C to 70°C. The TLC5628I is characterized for operation from –40°C to 85°C. The TLC5628C and TLC5628I do not require external trimming.

AVAILABLE OPTIONS								
PACKAGE								
TA	SMALL OUTLINE (DW)	PLASTIC DIP (N)						
0°C to 70°C	TLC5628CDW	TLC5628CN						
-40°C to 85°C	TLC5628IDW	TLC5628IN						



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### functional block diagram



## **Terminal Functions**

TERMINAL		1/0	DESCRIPTION
NAME	NO.	1/0	DESCRIPTION
CLK	5	I	Serial interface clock. The input digital data is shifted into the serial interface register on the falling edge of the clock applied to the CLK terminal.
DACA	2	0	DAC A analog output
DACB	1	0	DAC B analog output
DACC	16	0	DAC C analog output
DACD	15	0	DAC D analog output
DACE	7	0	DAC E analog output
DACF	8	0	DAC F analog output
DACG	9	0	DAC G analog output
DACH	10	0	DAC H analog output
DATA	4	I	Serial interface digital data input. The digital code for the DAC is clocked into the serial interface register serially. Each data bit is clocked into the register on the falling edge of the clock signal.
GND	3	I	Ground return and reference terminal
LDAC	13	I	Load DAC. When LDAC is high, no DAC output updates occur when the input digital data is read into the serial interface. The DAC outputs are only updated when LDAC is taken from high to low.
LOAD	12	I	Serial interface load control. When LDAC is low, the falling edge of the LOAD signal latches the digital data into the output latch and immediately produces the analog voltage at the DAC output terminal.
REF1	14	Ι	Reference voltage input to DAC A B C D. This voltage defines the analog output range.
REF2	11	Ι	Reference voltage input to DAC $E F G H$ . This voltage defines the analog output range.
V <sub>DD</sub>	6	Ι	Positive supply voltage



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### detailed description

The TLC5628 is implemented using eight resistor-string DACs. The core of each DAC is a single resistor with 256 taps, corresponding to the 256 possible codes listed in Table 1. One end of each resistor string is connected to GND and the other end is fed from the output of the reference input buffer. Monotonicity is maintained by use of the resistor strings. Linearity depends upon the matching of the resistor segments and upon the performance of the output buffer. Since the inputs are buffered, the DACs always present a high-impedance load to the reference sources. There are two input reference terminals; REF1 is used for DACA through DACD and REF2 is used by DACE through DACH.

Each DAC output is buffered by a configurable-gain output amplifier, that can be programmed to times 1 or times 2 gain.

On power up, the DACs are reset to CODE 0.

Each output voltage is given by:

 $V_{O}(DACA|B|C|D|E|F|G|H) = REF \times \frac{CODE}{256} \times (1 + RNG \text{ bit value})$ 

where CODE is in the range 0 to 255 and the range (RNG) bit is a 0 or 1 within the serial control word.

D7	D6	D5	D4	D3	D2	D1	D0	OUTPUT VOLTAGE
0	0	0	0	0	0	0	0	GND
0	0	0	0	0	0	0	1	(1/256) × REF (1+RNG)
•	•	•	•	•	•	•	•	•
•	•	•	•	•	•	•	•	•
0	1	1	1	1	1	1	1	(127/256) × REF (1+RNG)
1	0	0	0	0	0	0	0	(128/256) × REF (1+RNG)
•	•	•	•	•	•	•	•	•
•	•	•	•	•	•	•	•	•
1	1	1	1	1	1	1	1	(255/256) × REF (1+RNG)

Table 1. Ideal Output Transfer

### data interface

With LOAD high, data is clocked into the DATA terminal on each falling edge of CLK. Once all data bits have been clocked in, LOAD is pulsed low to transfer the data from the serial input register to the selected DAC as shown in Figure 1. When LDAC is low, the selected DAC output voltage is updated when LOAD goes low. When LDAC is high during serial programming, the new value is stored within the device and can be transferred to the DAC output at a later time by pulsing LDAC low as shown in Figure 2. Data is entered most significant bit (MSB) first. Data transfers using two 8-clock cycle periods are shown in Figures 3 and 4.



Figure 1. LOAD-Controlled Update (LDAC = Low)



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### Figure 4. LDAC-Controlled Update Using 8-Bit Serial Word

Table 2 lists the A2, A1, and A0 bits and the selection of the updated DACs. The RNG bit controls the DAC output range. When RNG = low, the output range is between the applied reference voltage and GND, and when RNG = high, the range is between twice the applied reference voltage and GND.

A2	A1	A0	DAC UPDATED
0	0	0	DACA
0	0	1	DACB
0	1	0	DACC
0	1	1	DACD
1	0	0	DACE
1	0	1	DACF
1	1	0	DACG
1	1	1	DACH

Table	2.	Serial	Input	Decode
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#### linearity, offset, and gain error using single-end supplies

When an amplifier is operated from a single supply, the voltage offset can still be either positive or negative. With a positive offset voltage, the output voltage changes on the first code change. With a negative offset the output voltage may not change with the first code depending on the magnitude of the offset voltage.

The output amplifier, therefore, attempts to drive the output to a negative voltage. However, because the most negative supply rail is ground, the output cannot drive below ground.

The output voltage remains at 0 V until the input code value produces a sufficient output voltage to overcome the inherent negative offset voltage, resulting in the transfer function shown in Figure 5.



Figure 5. Effect of Negative Offset (Single Supply)

This offset error, not the linearity error, produces the breakpoint. The transfer function would have followed the dotted line if the output buffer could drive below ground.

For a DAC, linearity is measured between the zero-input code (all inputs are 0) and the full-scale code (all inputs are 1) after offset and full scale are adjusted out or accounted for in some way. However, single-supply operation does not allow for adjustment when the offset is negative due to the breakpoint in the transfer function. So the linearity in the unipolar mode is measured between full-scale code and the lowest code that produces a positive output voltage.

The code is calculated from the maximum specification for the negative offset voltage.



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### equivalent of inputs and outputs



### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage (V <sub>DD</sub> – GND)	
Digital input voltage range, VID	GND – 0.3 V to $V_{DD}$ + 0.3 V
Reference input voltage range	
Operating free-air temperature range, T <sub>A</sub> : TLC5628C	0°C to 70°C
TLC5628I	–40°C to 85°C
Storage temperature range, T <sub>stg</sub>	–50°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

### recommended operating conditions

		MIN	NOM	MAX	UNIT
Supply voltage, V <sub>DD</sub>		4.75		5.25	V
High-level voltage, V <sub>IH</sub>		0.8 V <sub>DD</sub>			V
Low-level voltage, VIL				0.8	V
Reference voltage, V <sub>ref</sub> [A B C D E F G H]				V <sub>DD</sub> -1.5	V
Analog full-scale output voltage, $R_L = 10$ k	Ω		3.5		V
Load resistance, RL		10			kΩ
Setup time, data input, t <sub>SU(DATA-CLK)</sub> (se	ee Figures 1 and 2)	50			ns
Valid time, data input valid after $CLK\downarrow$ , $t_{V(I)}$	50			ns	
Setup time, CLK eleventh falling edge to L	me, CLK eleventh falling edge to LOAD, t <sub>su(CLK-LOAD)</sub> (see Figure 1) 50				
Setup time, LOAD <sup>↑</sup> to CLK↓, t <sub>SU(LOAD-CLK)</sub> (see Figure 1) 50					ns
Pulse duration, LOAD, $t_{W(LOAD)}$ (see Fig	ure 1)	250			ns
Pulse duration, LDAC, tw(LDAC) (see Fig	ure 2)	250			ns
Setup time, LOAD↑ to LDAC↓, t <sub>SU(LOAD</sub> -	LDAC) (see Figure 2)	0			ns
CLK frequency	· · · ·			1	MHz
Operating free air temperature	TLC5628C	0		70	°C
Operating free-air temperature, $T_A$	TLC5628I	-40		1	°C



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### electrical characteristics over recommended operating free-air temperature range, $V_{DD}$ = 5 V ± 5%, $V_{ref}$ = 2 V, $\times$ 1 gain output range (unless otherwise noted)

	PARAMETER	TEST	<b>CONDITIONS</b>	MIN	TYP	MAX	UNIT
Ιн	High-level input current	$V_I = V_{DD}$	$V_{I} = V_{DD}$			±10	μA
Ι <sub>Ι</sub>	Low-level input current	$V_{I} = 0 V$	$V_{I} = 0 V$			±10	μA
IO(sink)	Output sink current	Fach DAC ou	14 m 1 14	20			μA
IO(source)	Output source current	Each DAC ou	πραι	2			mA
C.	Input capacitance				15		ъГ
Ci	Reference input capacitance				15		pF
IDD	Supply current	$V_{DD} = 5 V$				4	mA
I <sub>ref</sub>	Reference input current	V <sub>DD</sub> = 5 V,	V <sub>ref</sub> = 2 V			±10	μΑ
EL	Linearity error (end point corrected)	$V_{ref} = 2 V,$	× 2 gain (see Note 1)			±1	LSB
ED	Differential-linearity error	$V_{ref} = 2 V,$	imes 2 gain (see Note 2)			±0.9	LSB
E <sub>ZS</sub>	Zero-scale error	$V_{ref} = 2 V,$	imes2 gain (see Note 3)	0		30	mV
	Zero-scale-error temperature coefficient	$V_{ref} = 2 V,$	× 2 gain (see Note 4)		10		μV/°C
E <sub>FS</sub>	Full-scale error	$V_{ref} = 2 V,$	× 2 gain (see Note 5)			±60	mV
	Full-scale-error temperature coefficient	$V_{ref} = 2 V,$	× 2 gain (see Note 6)		±25		μV/°C
PSRR	Power supply rejection ratio	See Notes 7 a	and 8		0.5		mV/V

NOTES: 1. Integral nonlinearity (INL) is the maximum deviation of the output from the line between zero and full scale (excluding the effects of zero code and full-scale errors).

2. Differential nonlinearity (DNL) is the difference between the measured and ideal 1 LSB amplitude change of any two adjacent codes. Monotonic means the output voltage changes in the same direction (or remains constant) as a change in the digital input code.

3. Zero-scale error is the deviation from zero voltage output when the digital input code is zero.

4. Zero-scale-error temperature coefficient is given by:  $ZSETC = [ZSE(T_{max}) - ZSE(T_{min})]/V_{ref} \times 10^{6}/(T_{max} - T_{min})$ .

5. Full-scale error is the deviation from the ideal full-scale output ( $V_{ref} - 1$  LSB) with an output load of 10 k $\Omega$ .

6. Full-scale error temperature coefficient is given by: FSETC = [FSE(T<sub>max</sub>) – FSE (T<sub>min</sub>)]/V<sub>ref</sub> × 10<sup>6</sup>/(T<sub>max</sub> – T<sub>min</sub>).

7. Zero-scale-error rejection ratio (ZSE RR) is measured by varying the V<sub>DD</sub> from 4.5 V to 5.5 V dc and measuring the proportion of this signal imposed on the zero-code output voltage.

8. Full-scale-error rejection ratio (FSE RR) is measured by varying the V<sub>DD</sub> from 4.5 V to 5.5 V dc and measuring the proportion of this signal imposed on the full-scale output voltage.

### operating characteristics over recommended operating free-air temperature range, $V_{DD} = 5 V \pm 5\%$ , $V_{ref} = 2 V, \times 1$ gain output range (unless otherwise noted)

	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Output slew rate	$C_L = 100 \text{ pF}, \qquad R_L = 10 \text{ k}\Omega$		1		V/µs
Output settling time	To $\pm 0.5$ LSB, C <sub>L</sub> = 100 pF, R <sub>L</sub> = 10 k $\Omega$ , See Note 9		10		μs
Large signal bandwidth	Measured at –3 dB point		100		kHz
Digital crosstalk	CLK = 1-MHz square wave measured at DACA-DACD		-50		dB
Reference feedthrough	See Note 10		-60		dB
Channel-to-channel isolation	See Note 11		-60		dB
Reference input bandwidth	See Note 12		100		kHz

NOTES: 9. Settling time is the time between a LOAD falling edge and the DAC output reaching full-scale voltage within ±0.5 LSB starting from an initial output voltage equal to zero.

10. Reference feedthrough is measured at any DAC output with an input code = 00 hex with a  $V_{ref}$  input = 1 V dc + 1  $V_{pp}$  at 10 kHz. 11. Channel-to-channel isolation is measured by setting the input code of one DAC to FF hex and the code of all other DACs to 00 hex

with  $V_{ref}$  input = 1 V dc + 1  $V_{pp}$  at 10 kHz. 12. Reference bandwidth is the -3 dB bandwidth with an input at  $V_{ref}$  = 1.25 V dc + 2  $V_{pp}$  and with a full-scale digital input code.



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### PARAMETER MEASUREMENT INFORMATION







## **TYPICAL CHARACTERISTICS**



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TEXAS

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**TYPICAL CHARACTERISTICS** 

Figure 13







Figure 15. Output Buffering Scheme



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#### **MECHANICAL DATA**

### DW (R-PDSO-G\*\*)

### PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013



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### **MECHANICAL DATA**

## N (R-PDIP-T\*\*)

### PLASTIC DUAL-IN-LINE PACKAGE

4040049/C 08/95



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-001 (20-pin package is shorter than MS-001)



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